

The ITS08F06 is a robust n-channel, enhancement mode insulated gate bipolar transistor (IGBT) designed for low power dissipation in a wide range of high voltage applications such as power supplies and motor drives. The high impedance gate simplifies gate drive considerations, allowing operation directly from low power control circuitry.

Fast rise and fall times allow very high frequency switching making the device suitable for modern systems employing high frequency switching.

Low saturation voltages minimise power dissipation, thereby reducing the cost of the overall system in which they are used.

The ITS is fully short circuit rated making it especially suited for motor control and other applications requiring short circuit withstand capacity. Each device in the Powerline range is available with or without an integral anti-parallel ultrafast soft recovery diode, see separate datasheet for co-pack device.

Typical applications include high frequency inverters for motor control, welding and heating apparatus. The Powerline range of IGBTs is also applicable to switched mode and uninterruptible power supplies.

FEATURES

- Enhancement Mode n-Channel Device
- High Switching Speed
- Low On-state Saturation Voltage
- High Input Impedance Simplifies Gate Drive
- TO220 and TO252 Package Options
- Short Circuit Rated

APPLICATIONS

- High Frequency Inverters
- Motor Control
- Switched Mode Power Supplies
- High Frequency Welding
- Heating/Cooking Apparatus

ORDERING INFORMATION

ITS08F06B	TO220
ITS08F06G	TO252 SMD (tape and reel)
ITS08F06H	TO252 SMD (tubes)

KEY PARAMETERS

V_{CES}	(max)	600V
$V_{CE(sat)}$	(typ)	2.1V
I_{C25}	(max)	14A
I_{C85}	(max)	8A
I_{CM}	(max)	16A
t_{sc}	(max)	10 μ s

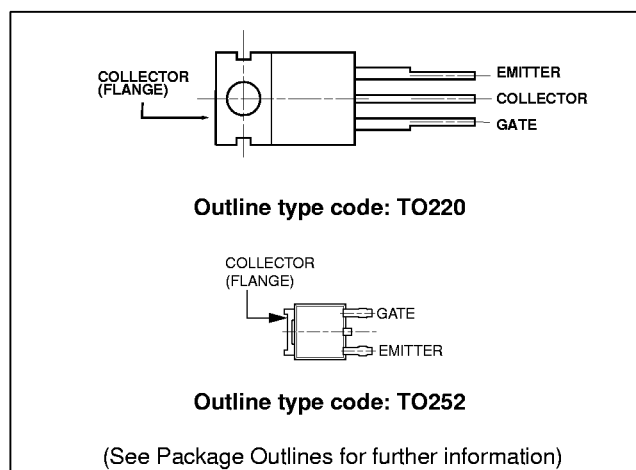


Fig.1 Pin connections - top view (not to scale)

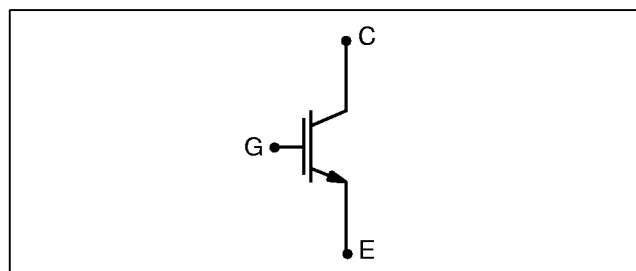


Fig.2 ITS08F06 circuit

ITS08F06

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

$T_{case} = 25^{\circ}\text{C}$ unless stated otherwise.

Symbol	Parameter	Test Conditions	Max.	Units
V_{CES}	Collector-emitter voltage	$V_{GE} = 0\text{V}$	600	V
V_{GES}	Gate-emitter voltage	-	± 20	V
I_{C25}	Continuous collector current	$T_{case} = 25^{\circ}\text{C}$	14	A
I_{C85}	Continuous collector current	$T_{case} = 85^{\circ}\text{C}$	8	A
I_{CM}	Pulsed collector current	1ms, $T_{case} = 85^{\circ}\text{C}$	16	A
P_{tot}	Power dissipation	$T_{case} = 85^{\circ}\text{C}$	30	W

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance	DC junction to case	-	2.1	$^{\circ}\text{C/W}$
T_{OP}	Operating junction temperature range	-	-40	150	$^{\circ}\text{C}$
T_{stg}	Storage temperature range	-	-40	150	$^{\circ}\text{C}$
-	Mounting torque	M3 screw	-	1.1	Nm

DC ELECTRICAL CHARACTERISTICS

$T_{case} = 25^{\circ}\text{C}$ unless stated otherwise.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
I_{CES}	Collector cut-off current	$V_{GE} = 0\text{V}$, $V_{CE} = 600\text{V}$	-	-	0.5	mA
I_{GES}	Gate leakage current	$V_{GE} = 20\text{V}$, $V_{CE} = 0\text{V}$	-	-	± 500	nA
$V_{GE(TH)}$	Gate threshold voltage	$I_C = 0.25\text{mA}$, $V_{CE} = V_{GE}$	4	6	7.5	V
$V_{CE(SAT)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{V}$, $I_C = 8\text{A}$	-	2.1	2.7	V
		$V_{GE} = 15\text{V}$, $I_C = 8\text{A}$, $T_J = 125^{\circ}\text{C}$	-	2.4	-	V

AC ELECTRICAL CHARACTERISTICS

$T_{\text{case}} = 25^{\circ}\text{C}$ unless stated otherwise.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
C_{ies}	Input capacitance	$V_{\text{CE}} = 25\text{V}, V_{\text{GE}} = 15\text{V}, f = 1\text{MHz}$	-	500	-	pF
C_{oes}	Output capacitance	$V_{\text{CE}} = 25\text{V}, V_{\text{GE}} = 15\text{V}, f = 1\text{MHz}$	-	130	-	pF
C_{res}	Reverse transfer capacitance	$V_{\text{CE}} = 25\text{V}, V_{\text{GE}} = 15\text{V}, f = 1\text{MHz}$	-	120	-	pF

INDUCTIVE SWITCHING CHARACTERISTICS - see figures 3 to 5

$T_{\text{case}} = 25^{\circ}\text{C}$ unless stated otherwise.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$t_{\text{d(ON)}}$	Turn-on delay time	$I_{\text{C}} = 8\text{A},$ $V_{\text{GE}} = \pm 15\text{V},$ $V_{\text{CE}} = 50\%V_{\text{ces}}$ $R_{\text{G(ON)}} = R_{\text{G(OFF)}} = 25\Omega$	-	100	-	ns
t_{r}	Rise time		-	16	-	ns
E_{ON}	Turn-on energy loss - per cycle		-	0.08	-	mJ
$t_{\text{d(OFF)}}$	Turn-off delay time		-	120	-	ns
t_{f}	Fall time		-	300	500	ns
E_{OFF}	Turn-off energy loss - per cycle		-	0.35	-	mJ

$T_{\text{case}} = 125^{\circ}\text{C}$ unless stated otherwise.

$t_{\text{d(ON)}}$	Turn-on delay time	$I_{\text{C}} = 8\text{A},$ $V_{\text{GE}} = \pm 15\text{V},$ $V_{\text{CE}} = 50\%V_{\text{ces}}$ $R_{\text{G(ON)}} = R_{\text{G(OFF)}} = 25\Omega$	-	100	-	ns
t_{r}	Rise time		-	16	-	ns
E_{ON}	Turn-on energy loss - per cycle		-	0.13	-	mJ
$t_{\text{d(OFF)}}$	Turn-off delay time		-	120	-	ns
t_{f}	Fall time		-	500	-	ns
E_{OFF}	Turn-off energy loss - per cycle		-	0.55	-	mJ

SHORT CIRCUIT RATING

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
t_{sc}	Short circuit withstand time	$T_{\text{c}} = 125^{\circ}\text{C}, V_{\text{GE}} = 15\text{V}, V_{\text{CE}} = 50\% V_{\text{CES}}$	-	-	10	μs

BASIC TEST CIRCUIT AND SWITCHING DEFINITIONS

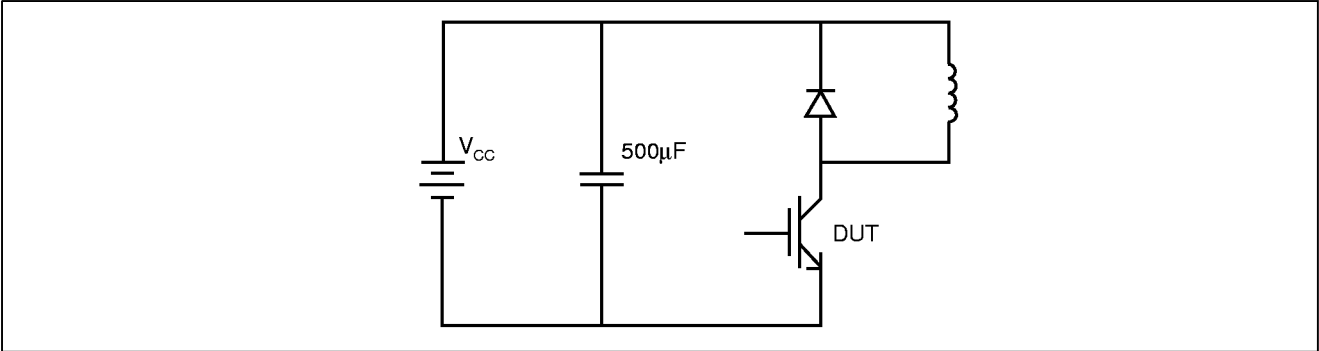


Fig.3 Basic d.c. chopper circuit

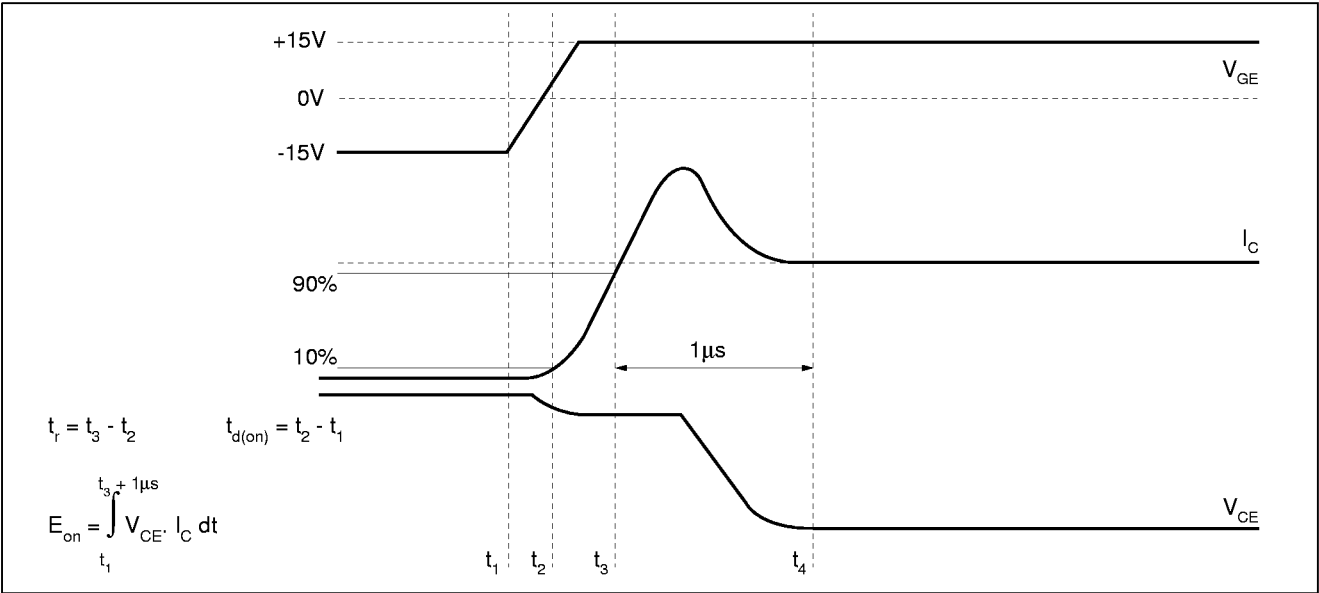


Fig.4 Turn-on characteristics

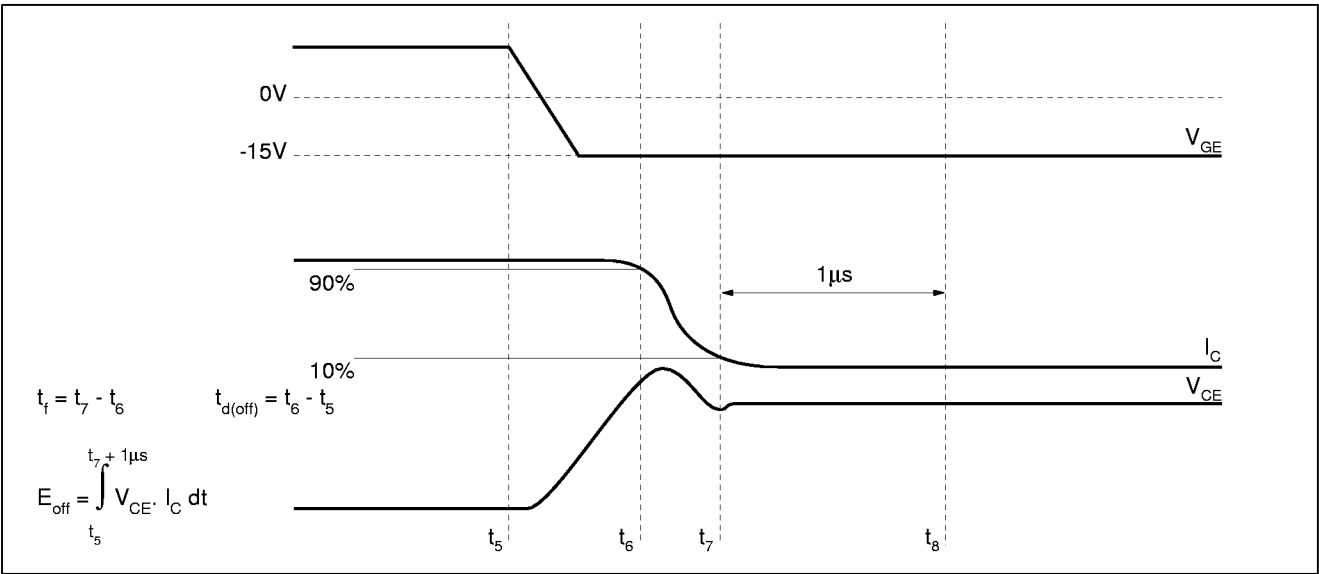
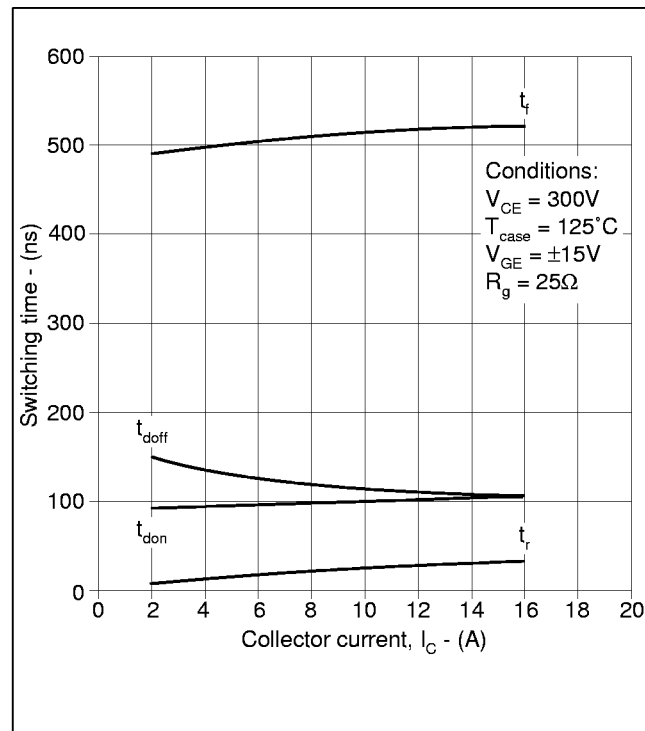
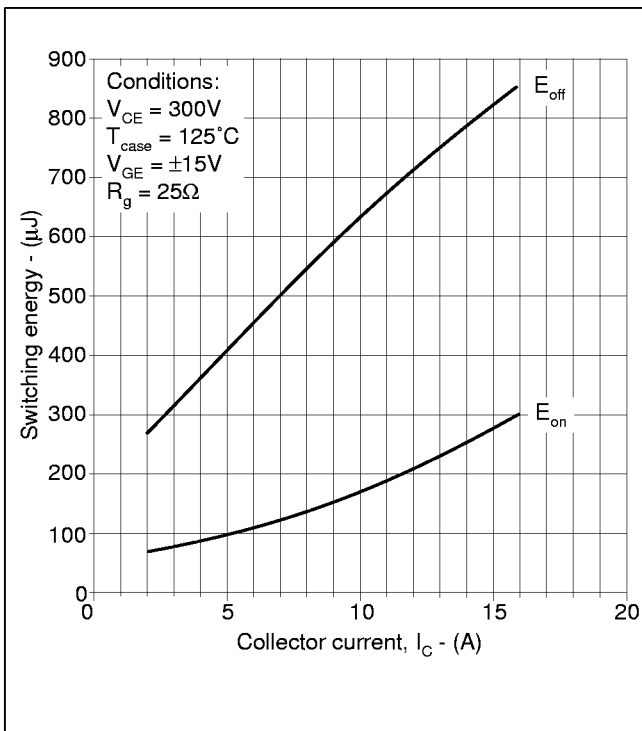
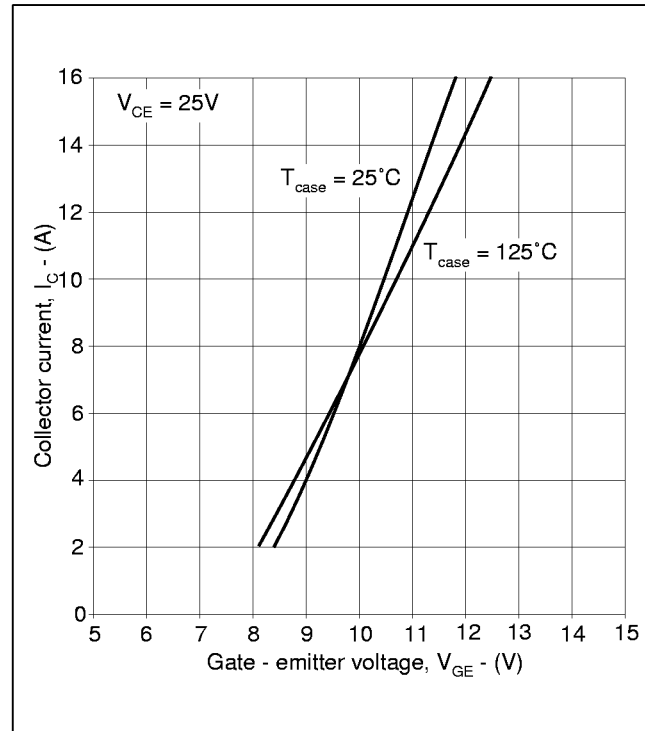
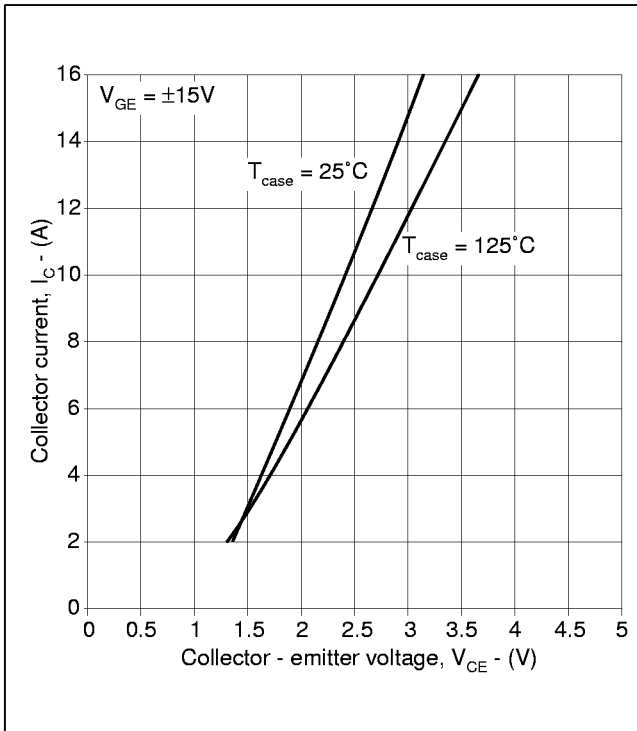


Fig.5 Turn-off characteristics

CURVES



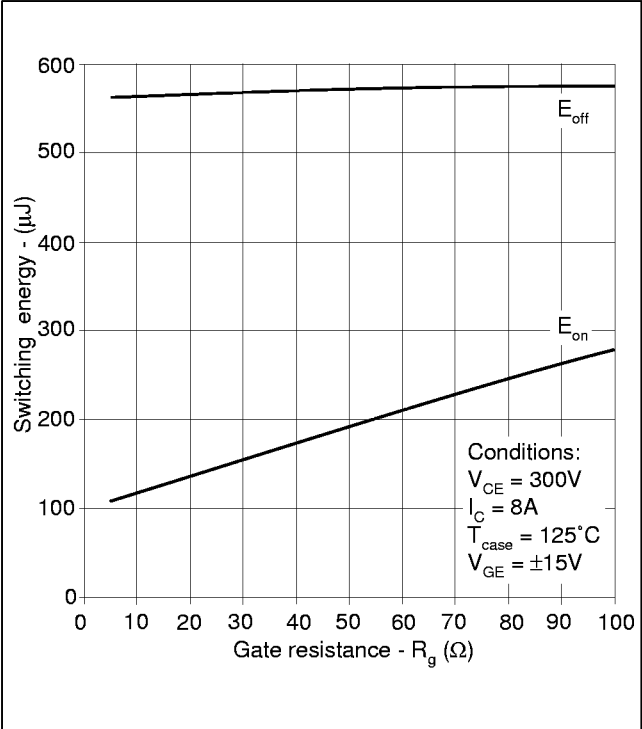


Fig.10 Typical switching losses vs gate resistance

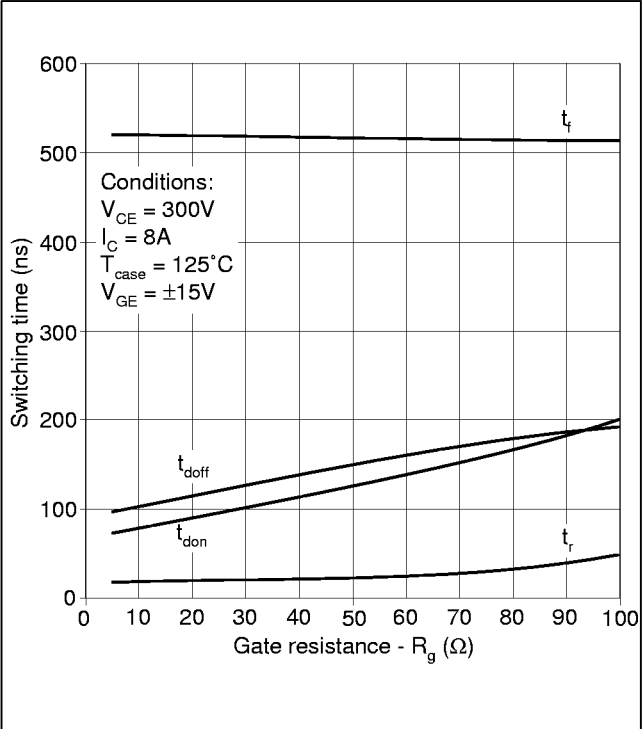


Fig.11 Typical switching times vs gate resistance

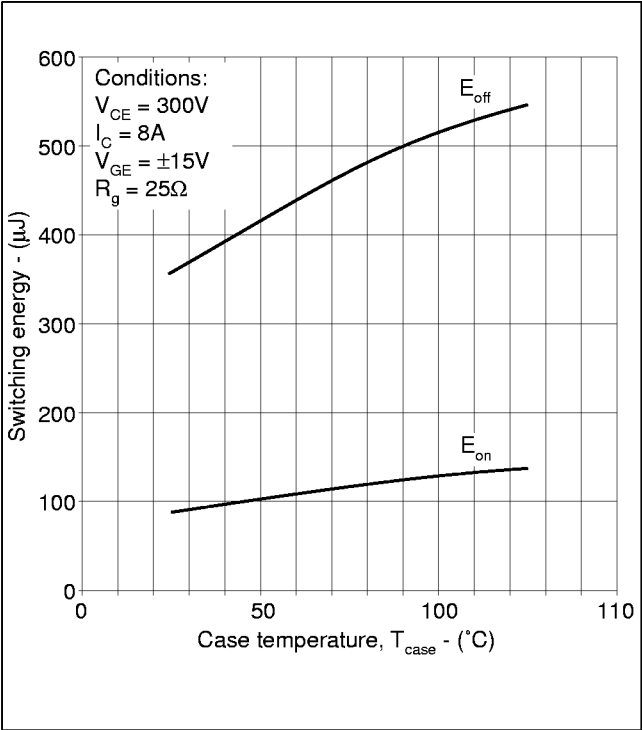


Fig.12 Typical switching losses vs case temperature

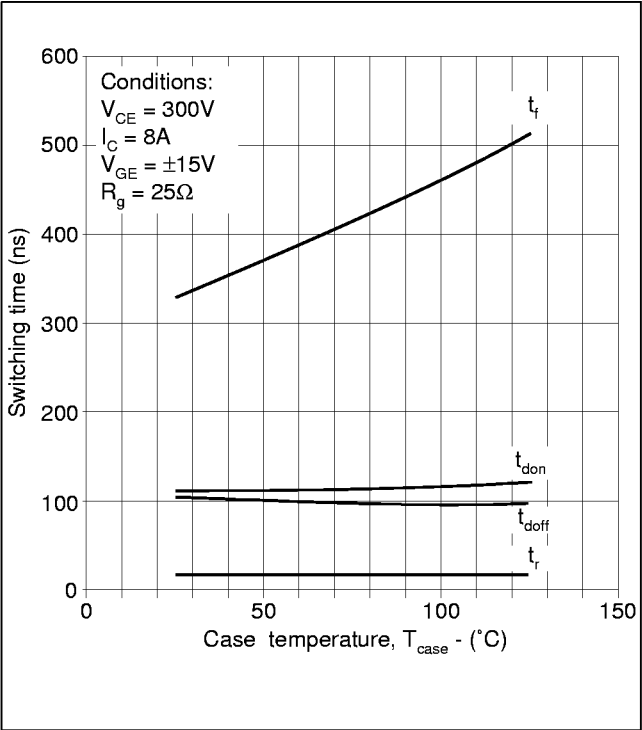


Fig.13 Typical switching time vs case temperature

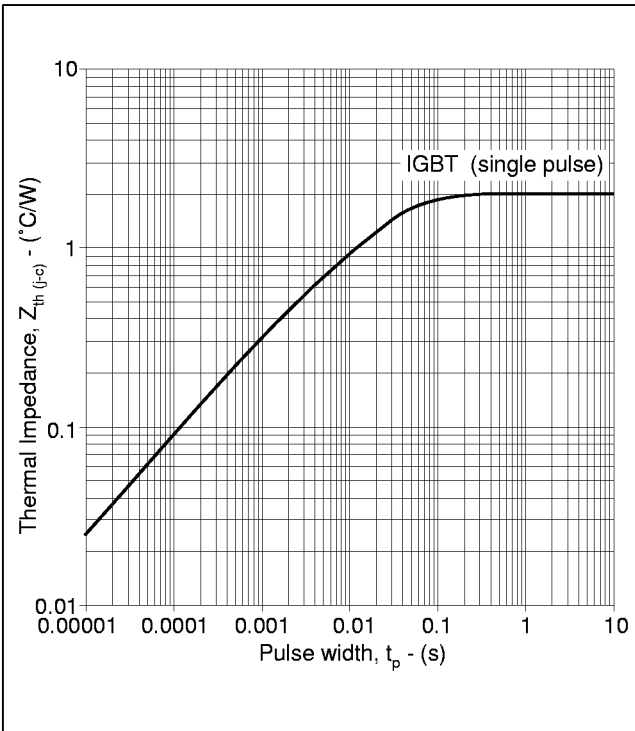


Fig.14 Transient thermal impedance - junction to case

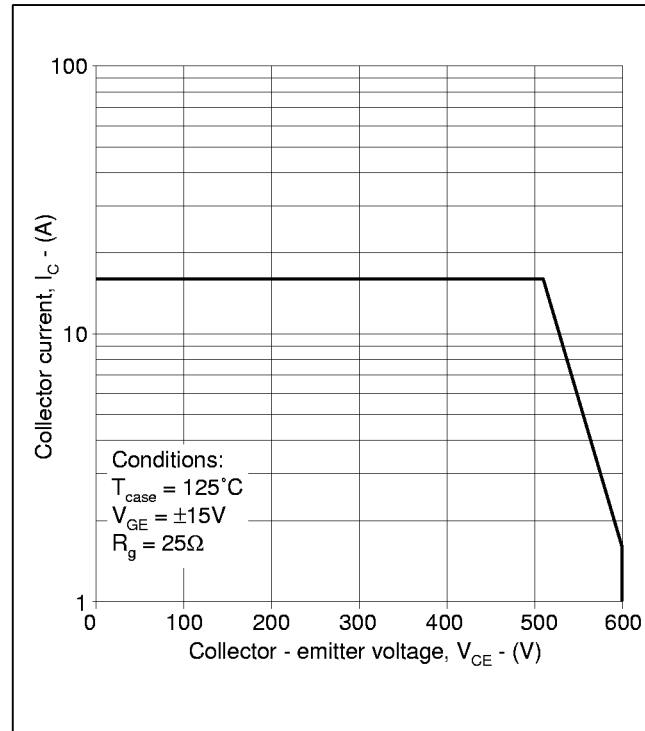
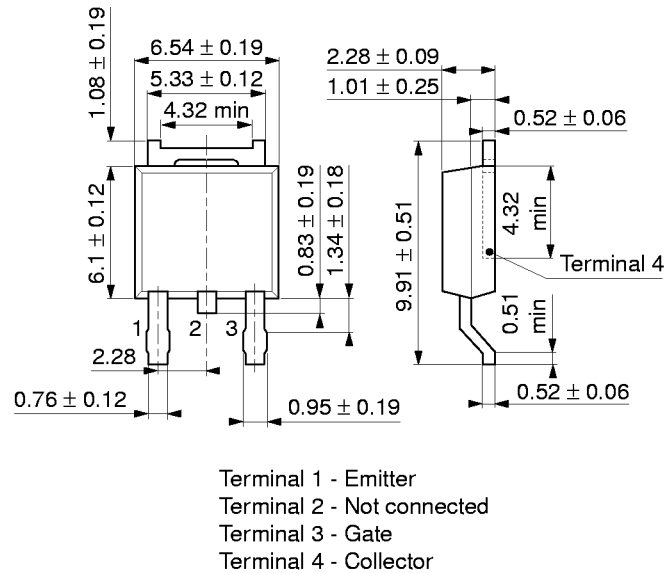


Fig.15 Reverse bias safe operating area

PACKAGE OUTLINE - TO252

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Technical drawing of a 3D printed part, showing front and side views with dimensions.

Front View Dimensions:

- Overall height: 15.0 ± 0.2
- Top section height: 2.85 ± 0.05
- Top section width: 10.0 ± 0.2
- Central hole diameter: $\varnothing 3.65 \pm 0.05$
- Distance from top edge to hole center: 12.15 ± 0.15
- Bottom section height: 3.05 min
- Bottom section width (left): 1.2 ± 0.05
- Bottom section width (right): 0.9 ± 0.05
- Bottom section width (center): 2.54

Side View Dimensions:

- Overall width: 4.45 ± 0.05
- Distance from left edge to hole center: 1.3 ± 0.05
- Maximum height of the top section: 6.3 max
- Overall height: 13.0 ± 0.3
- Bottom section width: 2.5 ± 0.1

Feature 4: A vertical slot or feature on the side view, indicated by a leader line labeled "4".


MITEL

SEMICONDUCTOR